# Low-profile 6.4mm height contributes to flexibility in set design





## Typical Specifications

Ite	ems	Specifications		
Rating (max.) (Re	sistive load)	10mA 5V DC		
Contact resistance	8-direction Center-push	500mΩ max.		
Operating angle (8	3-direction)	Each direction 12°±3°		
Travel (Center-pu	sh)	0.2±0.1mm		
0	Total with 8-direction	100,000 cycles		
Operating life	Center-push	100,000 cycles		

#### Product Line

Product No.	Maximum	Operatii	ng force	Minimum order unit (pcs.)		
	resolution	Direction	Center-push	Japan	Export	
RKJXL100401V	1V 8 10		4.5±1N	800	1,600	

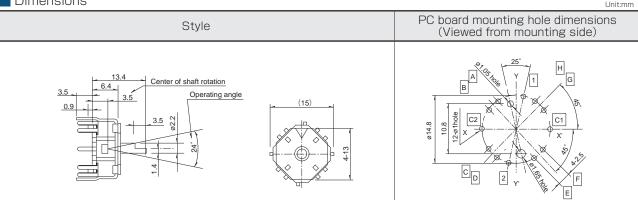
## Packing Specifications

## Tray

Number of pa	Export package	
1 case / Japan	measurements (mm)	
800	1,600	532×379×167

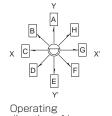
## Dimensions

Unit:mm



## Output Relation Chart Between Lever Position and ON Position.

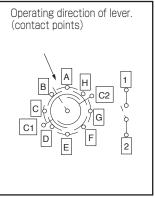
Terminal The direction of the operation	А	В	С	D	E	F	G	Н	C1	C2	1	2
Α	ON								ON			
В		ON							ON			
С			ON						ON			
D				ON					ON			
Е					ON					ON		
F						ON				ON		
G							ON			ON		
Н								ON		ON		
Center Push											ON	ON



direction of lever.

Shorting areas exist between adjacent terminals
 Between H and A, and D and E, both C1 and C2 are connected

# Circuit Diagram



	Type Switch type							
Ç	Series		RKJXT1F	RKJXM	RKJXW	RKJXL		
Photo		<b>.</b> c5.	**	类	**			
D		W	17	11	36	- 13		
Dimensior (mm)		D		11	48.5	10		
		Н	10.5	6.6	26.5	6.4		
Sha	ft materia	al		Me	etal			
	nal resol		4-direction		8-direction			
Directional (tac	operating tile feeling			With		Without		
	turn mecha			W	ith			
Center	-push sw	itch		W	ith			
Е	ncoder		With	Without	With	Without		
Operating temperature range		e range		-30°C to +70°C				
Directional operation		operation	Total with 4-direction	Total with 8-direction	30,000 cycles for each direction	on 8 directions total: 100,000 cycles		
Operating life	Center	-push	50,000 cycles	100,000 cycles	30,000 cycles	100,000 cycles		
	Enco	oder	15,000 cycles	_	30,000 cycles	_		
Auto	motive us	se	•	•	•	•		
Life cyc	e (availal	bility)	2	<b>*</b> 2	<b>★</b> 2	<b>*</b> 2		
Rating (ma	x.) (Resistiv	e load)		10mA	5V DC			
	Output	voltage	_	_	_	_		
Electrical	Encoder re	esolution	15pulses/360°	_	15pulses/360°	_		
performance	Insulation r	esistance						
	Voltage	e proof	250V AC	for 1min.	360V AC for 2s	300V AC for 1min. or 360V AC for 2s		
	Direct operatin		40±25mN·m	Direction A, B, C, D 30±20mN·m	2.5±1.5N	10±7mN·m		
				25±20mN·m		45.00		
Mechanical performance	Push opera	_	5±2N	3±1	1.5N	4.5±1N		
	Encoder det	-	15±8mN·m	- Imin	30±20mN·m —			
	Terminal	Push / pull directions	100N (Push/Pull)	100N (Push), 50N (Pull)	100N (Push)	100N (Push), 50N (Pull)		
	Actuator strength	Operating	0.4N·m	0.3N·m	50N	100N (Push), 50N (Pull)		
	Co	direction	OTIVIII		500h	10014		
Environmental	Dry h			85°				
performance .	Damp				95%RH 500h			
		Hout	000			46.		
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# Note

• Indicates applicability to all products in the series.

# Switch Type Multi Control Devices / Soldering Conditions

### Reference for Manual Soldering

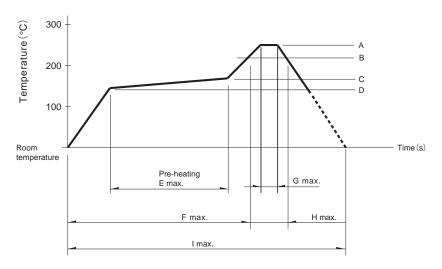
Series	Tip temperature	Soldering time	No. of solders
RKJXT1F, RKJXM, RKJXL, SLLB, SLLB5, SRBE, SKRH	350±5℃	3s max.	1 time

## ■ Reference for Dip Soldering

Series	Preheating		Dip so	No. of solders	
Jenes	Soldering surface temperature	Heating time	Soldering temperature	Soldering time	No. or soluers
RKJXT1F, RKJXM	100°C max.	2 min. max.	260±5℃	5±1s	2 time max.
RKJXL	120°C max.	70s max.	260°C max.	6s max.	2 time max.

## Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple  $\phi$ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
- 3. Temperature profile



Series	А	В	С	D	Е	F	G	Н	I	No. of reflows
SLLB5	250℃	230℃	150℃	150℃	_	2 min.	_	30s	_	1 time
SLLB, SRBE	260℃	230℃	180℃	150℃	2 min.	_	_	40s	_	1 time
SKRH	260℃	230℃	180℃	150℃	2 min.	_	3s	40s	3-4 min.	2 times

#### Notes

- 1. The above temperature shall be measured on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size thickness of PC boards and others. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.